CLAIMS

1. A resin composition comprising:

a resin component comprising an epoxy resin, a diamine compound, and a polyimide resin; and

a dielectric filler composed of a complex metal oxide comprising at least two elements selected from the group consisting of Ba, Ti, Sr, Pb, Zr, La, Ta, and Bi, the content of the dielectric filler being 70 to 85 parts by weight on the basis of 100 parts by weight of solid content in the resin composition,

wherein the content of the polyimide resin is 20 to 40 parts by weight on the basis of 100 parts by weight of the resin component,

wherein the content of the epoxy resin is 45 to 60 parts by weight on the basis of 100 parts by weight of the resin component, and

wherein the content of the diamine compound is determined such that when the number of epoxy groups in the epoxy resin is set to 1, the number of active hydrogen groups in the diamine compound is 0.5 to 1.5.

2. The resin composition according to claim 1, wherein the complex metal oxide comprises at least one selected from the group consisting of $BaTiO_3$, $SrTiO_3$, $Pb(Zr,Ti)O_3$, $PbLaTiO_3$, PbLaZrO, and $SrBi_2Ta_2O_9$.

3. The resin composition according to claim 1 or 2, wherein the complex metal oxide is $BaTiO_3$.

4. The resin composition according to any one of claims 1 to 3, wherein the content of the diamine compound is determined such that when the number of epoxy groups in the epoxy resin is set to 1, the number of active hydrogen groups in the diamine compound is 0.8 to 1.2.

5. A resin-coated copper foil comprising a copper foil and the resin composition according to any one of claims 1 to 4, the resin composition being provided on at least one side of the copper foil.

6. A dielectric layer comprising the resin composition according to any one of claims 1 to 4 that is cured.

7. The dielectric layer according to claim 6, wherein the dielectric layer has a thickness of 0.2 to 30 μm.

8. The dielectric layer according to claim 6, wherein the dielectric layer has a thickness of 1 to 10 μm.

9. A copper-clad laminate comprising, in sequence, a first copper foil, the dielectric layer according to any one of claims 6 to 8, and a second copper foil.

10. A capacitor device comprising the dielectric layer according to any one of claims 6 to 8.

11. A capacitor-embedded printed circuit board comprising the dielectric layer according to any one of claims 6 to 8.

12. A method of producing a resin-coated copper foil, comprising:

coating a copper foil with a resin composition comprising a resin component comprising an epoxy resin, a diamine compound, and a polyimide resin; and a dielectric filler composed of a complex metal oxide comprising at least two elements selected from the group consisting of Ba, Ti, Sr, Pb, Zr, La, Ta, and Bi, the content of the dielectric filler being 70 to 85 parts by weight on the basis of 100 parts by weight of solid content in the resin composition; wherein the content of the polyimide resin is 20 to 40 parts by weight on the basis of 100 parts by weight of the resin component, wherein the content of the epoxy

resin is 45 to 60 parts by weight on the basis of 100 parts by weight of the resin component, and wherein the content of the diamine compound is determined such that when the number of epoxy groups in the epoxy resin is set to 1, the number of active hydrogen groups in the diamine compound is 0.5 to 1.5, and

drying the resin composition.